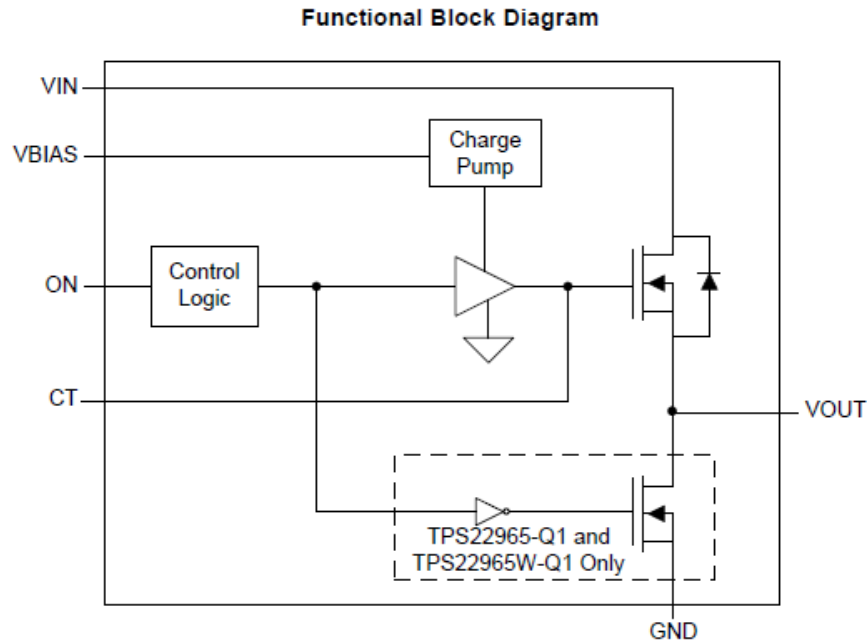


# Functional Safety FIT Rate, Failure Mode Distribution TPS22965-Q1

## 5.5-V, 4-A, 16-mΩ On-Resistance Load Switch



| Failure Rate Mission Profile (1) | Per 10 <sup>9</sup> Hours (FIT) |
|----------------------------------|---------------------------------|
| Total FIT Rate                   | 4                               |
| Die FIT Rate                     | 2                               |
| Package FIT Rate                 | 2                               |

| FIT Siemens Norm SN29500 (2) |                        |                         |                                |
|------------------------------|------------------------|-------------------------|--------------------------------|
| Table                        | Category               | Ref FIT $\lambda_{ref}$ | Ref Virtual Tj $\theta_{vj,1}$ |
| Table 5                      | Digital, Analog, Mixed | 20 FIT                  | 55 C                           |

| Failure Modes                                | Failure Mode Distribution (%) |                             |
|--|-------------------------------|-----------------------------|
|  | TPS22965N-Q1<br>TPS22965NW-Q1 | TPS22965-Q1<br>TPS22965W-Q1 |
| VOUT open or HIZ                             | 40                            | 20                          |
| VOUT to GND                                  | 20                            | 40                          |
| VOUT outside specification (voltage or time) | 30                            | 30                          |
| VOUT stuck on                                | 5                             | 5                           |
| Pin to Pin short any two pins                | 5                             | 5                           |

## **(1) Failure Rate, Mission Profile and Failure Modes Distribution**

The failure rate and mission profile information come from reliability modeling for Integrated circuits in Reliability data handbook IEC TR 62380 and ISO 26262 Part 11

Mission Profile: Motor Control from Table 11

Power dissipation 5 mW

Climate type: World-wide Table 8

Package factor lambda 3 Table 17b

Substrate Material: FR4

EOS FIT rate assumed = 0

## **(2) Reference failure rate, Virtual (equivalent) junction temperature**

The reference failure rate and virtual junction temperature come from Siemens Norm SN29500-2 tables 1-5.

Failure rate for user mission profile is calculated using the reference failure rate and virtual junction temperature and following the calculation information in SN29500-2 section 4.

The failure mode distribution estimation comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment. The failure rates listed reflect random failure events and do not include failures due to misuse or over stress.

TPS22965-Q1 is a catalog product and not compliant to ISO-26262 standards.

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